

Tool ID: 206  
Tool Location: 107

Equipment Information Sheet

# Trion Minilock III ICP Etcher

**Manager:** Jeremy Clark    **607-254-6487**

**Backup:** Philip Schneider    **607-254-4931**

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

**SAFETY**

- User must remain in the lab while the plasma is running
- System uses Chlorine & Boron Trichloride

**USAGE RESTRICTIONS**

- No buddy system restrictions for normal operation

**SCHEDULING/SIGN-UP RESTRICTIONS**

*Minimum Tool Time: 30 minutes*

- No scheduling restrictions

**MATERIALS COMPATIBILITY CATEGORY**

Tool Category 5: Class A and B Metals and Compounds	
Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

**High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.**

**Additional Material Restrictions and Exceptions**

- No high vapor pressure materials (Pb, ITO, etc.)
- No gold exposed to the plasma
- Pieces should be mounted to sapphire carrier wafer (4)

*Last Updated: 07/30/2025*